

描述 / Descriptions

TO-92 塑封封装单向可控硅。Thyristor in a TO-92 Plastic Package.

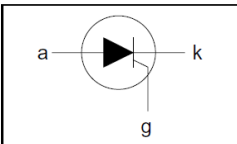
特征 / Features

阻断电压高、浪涌电流承受能力强。
High Blocking Voltage, High Surge Current Capability.

用途 / Applications

应用于高压控制电路。
Applied to high Voltage control circuit.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN 1 : Anode PIN 2 : Gate PIN 3 : Cathode

放大及印章代码 / h_{FE} Classifications & Marking

见印章说明。See Marking Instructions.

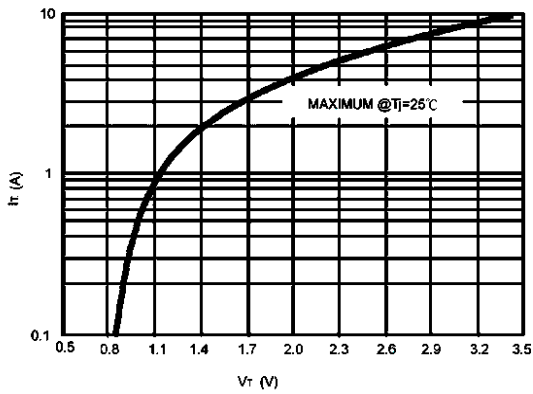
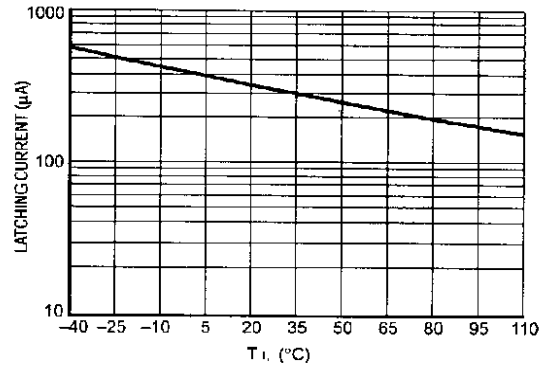
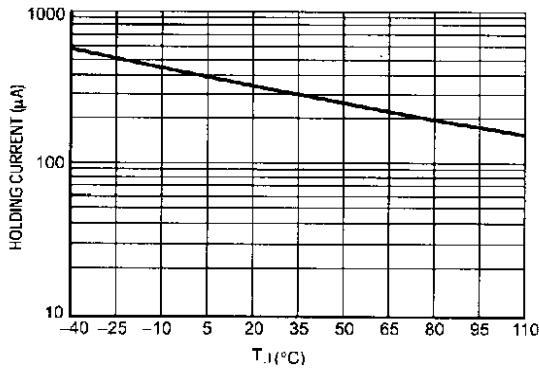
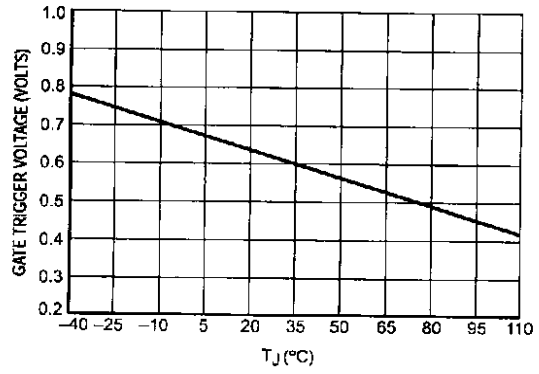
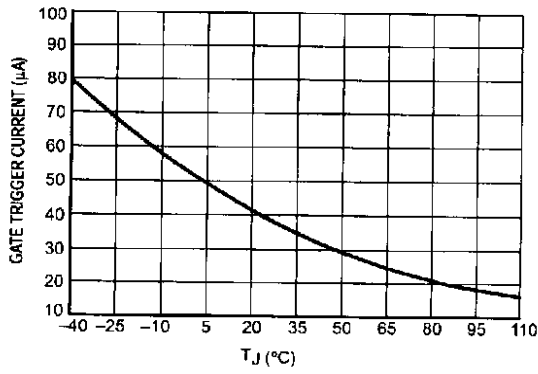
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Repetitive peak off-state voltages	V_{DRM}	$T_j=40$ to $125^{\circ}C$ ($R_{gk}=1k\Omega$)	400	V
RMS on-state current	$I_{T(RMS)}$	$T_c=40^{\circ}C$	0.8	A
Average on-state current	$I_{T(AV)}$	Half cycle=180 $T_c=40^{\circ}C$	0.6	A
Repetitive gate current	V_{GRM}	$I_{GR}=10\mu A$	1.0	V
Peak gate current	I_{GM}	10 μs Max	0.1	A
Peak gate power	$P_{G(AV)}$	20ms Max	200	mW
Junction Temperature	T_j		-40~125	$^{\circ}C$
Storage Temperature Range	T_{stg}		-40~125	$^{\circ}C$

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Repetitive peak off-state current	I_{DRM}	$V_{DRM}(R_{GK}=1K\Omega)$ $T_j=125^{\circ}C$			0.2	mA
Repetitive peak off-state current	I_{DRM}	$V_{DRM}(R_{GK}=1K\Omega)$ $T_j=25^{\circ}C$			5.0	μA
On-state voltage	V_T	$I_T=0.6A$			1.7	V
		$I_T=0.8A$			2.2	V
On-state voltage	$V_{T(TO)}$	$T_j=125^{\circ}C$			0.95	V
Gate trigger current	I_{GT}	$V_D=6.0V$ $R_L=10\Omega$			200	μA
Gate trigger voltage	V_{GT}	$V_D=6.0V$ $R_L=10\Omega$			0.8	V
Holding current	I_H	$V_D=6.0V$			5	mA
Off-state leakage current	V_{GD}	$V_{DRM}=400V$ $R_{GK}=1K\Omega$ $T_j=110^{\circ}C$	0.1			V

电参数曲线图 / Electrical Characteristic Curve



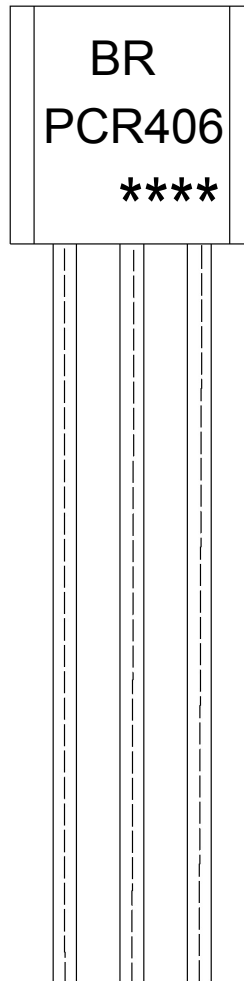
外形尺寸图 / Package Dimensions

TO-92

Unit: mm



印章说明 / Marking Instructions



说明：

BR： 为公司代码

PCR406： 为产品型号

****： 为生产批号代码，随生产批号变化。

Note:

BR: Company Code.

PCR406: Product Type.

****: Lot No. Code, code change with Lot No.

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

散件包装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-92	1,000	10	10,000	5	50,000	135×190	237×172×102	560×245×195
	1,000	10	10,000	10	100,000	135×190	237×172×102	560×245×375

编带包装 / AMMO

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)	
	Units/tape 只/纸带	Tape/Inner Box 纸带/盒	Rows/Inner Box 纸带层/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Inner Box 盒	Outer Box 箱
TO-92	3,000	1	120	10	30,000	328×230×42	小箱 480×346×235, 大箱 547×407×268

使用说明 / Notices